

# Claims

- [c1] 1. A package structure that is compatible with a cooling system, comprising:
- a carrier;
  - at least a chip, arranged on the carrier and electrically connected to the carrier;
  - a mold compound, covering the chip and one surface of the carrier; and
  - a cooling tubule disposed within the mold compound, wherein the cooling tubule is connected to the cooling system, wherein the cooling system is a closed system and a fluid driven by a pump circulates within the cooling tubule and the cooling system.
- [c2] 2. The package structure of claim 1, wherein the cooling system comprises a cooling tubing and the cooling tubule is connected to the cooling tubing.
- [c3] 3. The package structure of claim 1, wherein the fluid is selected from the group consisting of water, a coolant and a gas.
- [c4] 4. The package structure of claim 1, wherein the cooling system further comprises a cooler connected to the

cooling tubing.

- [c5] 5. The package structure of claim 1, wherein a material of the mold compound includes thermosetting plastics.
- [c6] 6. The package structure of claim 1, wherein a material of the mold compound includes an epoxy resin.
- [c7] 7. A package structure that is compatible with a cooling system, comprising:
  - a carrier;
  - at least a chip, arranged on the carrier and electrically connected to the carrier;
  - a mold compound, covering the chip and one surface of the carrier; and
  - a cooling tubule disposed on an outer surface of the mold compound, wherein the cooling tubule is connected to the cooling system, wherein the cooling system is a closed system and a fluid driven by a pump circulates within the cooling tubule and the cooling system.
- [c8] 8. The package structure of claim 7, wherein the cooling system comprises a cooling tubing and the cooling tubule is connected to the cooling tubing.
- [c9] 9. The package structure of claim 7, wherein the fluid is selected from the group consisting of water, a coolant and a gas.

- [c10] 10. The package structure of claim 7, wherein the cooling system further comprises a cooler connected to the cooling tubing.
- [c11] 11. The package structure of claim 7, wherein a material of the mold compound includes thermosetting plastics.
- [c12] 12. The package structure of claim 7, wherein a material of the mold compound includes an epoxy resin.